	1. PCN	basic data				
	Name Customer:					
Customer	Contact Email address	5:				
Melexis INSPIRED ENGINEERING	Site submitting the change:					
	Affected site(s):	Melexis Supplier	Melexis leper	Melexis Erfurt	Melexis Sofia	
1.2 PCN No.	MCM-5707					
1.3 Title of PCN	Business Continuity Pla	an Unisem E	Batam Products			
1.4 Product Category	Active Components - Ir	ntegrated Ci	rcuits			
1.5 Issue date	7/16/2019					
1.6 PCN revision history (optional)	1.7 Issue date of	1.8 Delta t	o previous revision (optior	nal)		
V1.0	7/15/2019	Initial PCN				
V2.0		Initial PCN				
V3.0	4/8/2020	Final PCN	- TH8056 in SOIC8 GR			
	2. PC	N Team				
2.1 Contact supplier						
2.1.1 Name	pcn_mlx (Lisa Vanhee	rswynghels)				
2 1 2 Phone	+32 57 22 62 07					

2.1.2 Phone	+32 57 22 62 07	32 57 22 62 07			
2.1.3 Email	pcn_mlx@melexis.com	cn_mlx@melexis.com			
2.2 Team supplier (optional)					
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)			
Hanne Thielens Customer Communication Coordination		hth@melexis.com			
Vincent Vanzeveren Global Quality Manager		vvn@melexis.com			
Karen Stinckens Global Purchasing Manager		kss@melexis.com			
Tim Vangerven Package Architect		tmv@melexis.com			

Arnaud De Functional	evos Safety and Reliability Manager		ade@melexis.com
		3. Changes	
No.	3.0 Ident	3.1 Category	3.2 Type of change
#1	SEM-PA-18	PROCESS - ASSEMBLY	Move of all or part of assembly to a different location/site/subcontractor
#2	SEM-PA-07	PROCESS - ASSEMBLY	Die attach material
#3	SEM-PA-16	PROCESS - ASSEMBLY	Change of direct material supplier
#4	SEM-PA-19	PROCESS - ASSEMBLY	Die Scribe or separation

4. Description of change					
	Old	New			
Change #1	Assembly house location : Unisem Batam (Indonesia)	Assembly house location : See section 11.			
Change #2	CRM1076	Ablebond 8290			
Change #3		Leadframe supplier: Mitsui, ASM, PSMC Die attach supplier: Henkel Gold wire supplier: Heesung,MKE			
Change #4	die sawing method: Single	die sawing method: Dual			
4.6 Anticipated impact on form, fit, function, reliability or processability?	Based on Risk Assessment including AEC-Q100 and ZVEI guidelines Use of package generic qualification data (from the assembly houses and Melexis) considering Automotive arades, Assembly Bill-of-Material & Bill-of-Process and Wafer Technology Whenever possible, re-use of Melexis qualified Bill-of-Material & Bill-of-Process will be applied"				
4.7 Reference parts with customer number					

5. Reason / motivation for change					
Discontinuation communication from Unisem about operations closure at Unisem Batam by 30-Sep-					
5.1 Motivation	2019.				

	On 28-Jun-2019 Melexis received formal notification about Unisem Batam' Operations discontinuation (see Melexis letter dated 01-Jul-2019). Melexis is using Unisem Batam as subcontractor for the assembly of several products. Subsequently, Melexis has decided to execute its Business Continuity Plan and activate alternative sources to the fullest extent.
5.2 Additional explanation (optional)	

6. Marking of parts / traceability of change					
Traceability through lot number and shipment date.					
6.1 Description					

7. Timing / schedule					
7.1 Date of qualification results	Qualification report is available	see attached			
7.2 Last order date (optional)	Closed				
7.3 Last delivery date (optional)	Q2 2020				
7.4 Intended start of delivery	Apr-20				
	Yes available (date an	d/or types):			
7.5 Qualification samples available?					
7.6 Customer feedback required until	20-Apr-2020				

8. Qualification / validation						
<ul> <li>Based on Risk Assessment including AEC-Q100 and ZVEI guidelines</li> <li>Use of package generic qualification data (from the assembly houses and Melexis) considering</li> <li>Automotive Grades, Assembly Bill-of-Material &amp; Bill-of-Process and Wafer Technology</li> <li>Whenever possible, re-use of Melexis qualified Bill-of-Material &amp; Bill-of-Process will be applied"</li> </ul>						
8.2 Qualification report and qualification results	available (see attachment) As per attached report: result PASS					

9. Input to customer for risk assessment process

10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)

BOM & BOP Risk Assessment SOIC8\_Amkor.pdf TH8056\_SO8\_AEC\_Q100\_Rev\_H\_Qualification\_Report.pdf

11. Affected parts									
11.1 Current	11.1 Current				11.2 New (if applicable)				
11.1.1 Custom Part No.	er 11.1.2 Supplier Part Name	11.1.3 Assem bly House	11.1.4 Package Name	11.1.5 Part Desc (Opt)	11.1.6 Addtl Part Info (Opt)	11.2.2 Supplier Part Name	11.2.3 Assembly House	11.2.4 Pkg Name	11.2. 6 Addtl Part Info (opt)
N/A	TH8056KDC-AAA-008-RE	Unisem	SOIC8 GR			TH8056KDC-AAA-008-RE	Amkor, Philippines	SOIC8	